

Structalit® 5604 is a thermally curing, one component SMD adhesive, showing fast curing properties at low temperatures and an excellent storage stability - 9 months at 5° C. The resin may tend to crystallize during storage, however this process is reversible at 40° C within one hour. The SMD adhesive shows a solid shock behaviour. The application works fine without any problems, when using common industrial techniques: dispensers, screenprint, needle transfer. The product can be used as SMD adhesive for soldering temperatures in short processes (max 5 minutes) at temperatures up to 270° C.

Technical Data

Color red
 Resin 1K-Epoxy

UNCURED PROPERTIES

Viscosity(Bohlin CVO / 25°C γ=10 1/s) [mPa*s]	PE-Norm P029	25000 to 40000
Flash point [°C]	PE-Norm P050	> 100
Density [g/cm³]	PE-Norm P051	approx. 1.1

Thermal Curing

2 minutes at	150 °C
5 minutes at	120 °C
15 minutes at	110 °C
45 minutes at	100 °C

CURED PROPERTIES

Temperature Resistance [°C]	PE-Norm P030	-40 to 180
Hardness Shore D	PE-Norm P052	80 to 90
Volume resistivity [Ohm x cm]	ASTM-D-257-93	1E+12
TG DSC [°C]	PE-Norm P009	115 to 135
Dielectric Constant [10kHz]	PE-Norm P054	3.3

Our data sheets have been compiled to the best of our knowledge. The information included in our data sheets is exclusive information for the intended user and describes characteristics, with no declaration of commitment. We recommend trials in order to confirm that our products satisfy the particular application requirements. For an additional technical consultation, please contact our RD department. In general, for guarantee claims, please refer to our standard terms and conditions.

Adhesives
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